AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A tape carrier type semiconductor device comprising:

a flexible substrate on whose surface wiring is formed; and

a driver circuit which is mounted on said flexible substrate and drives a device connected to said flexible substrate,

wherein said flexible substrate includes:

a first slit for releasing stress, said first slit having a connector ~~situated intermediate thereto~~ for connecting ~~both sides~~ parts of the first slit ~~to reduce warpage~~ and separating said parts in a width-wise direction of said flexible substrate; and

a second slit having no connector, for folding said flexible substrate.

2. (Currently Amended) The tape carrier type semiconductor device according to claim 1, wherein ~~the first slit includes~~ said connector comprises a plurality of connectors.

3. (Currently Amended) The tape carrier type semiconductor device according to claim 2, wherein said parts of the slit, which are separated from each other at the connector, are diverged from each other at the connector in a direction perpendicular to the slit.

4. (Currently Amended) The tape carrier type semiconductor device according to claim 3, wherein said ~~flexible substrate includes~~ first slit comprises a plurality of first slits.

5. (Previously Presented) The tape carrier type semiconductor device according to claim 4, wherein said second slit comprises a plurality of second slits.

6. (Previously Presented) The tape carrier type semiconductor device according to claim 4, wherein said flexible substrate includes a rib which is formed substantially perpendicular to the plurality of first slits.

7. (Previously Presented) The tape carrier type semiconductor device according to claim 4, wherein a portion of said flexible substrate is changed in shape, thereby to form a rib.

8. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate includes a rib formed substantially perpendicular to the first slit.

9. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein a portion of said flexible substrate is changed in shape, thereby to form a rib.

10. (Currently Amended) A tape carrier type semiconductor device comprising:

a flexible substrate on whose surface wiring is formed; and

a driver circuit which is mounted on said flexible substrate and drives a device connected to said flexible substrate,

wherein said flexible substrate includes:

a first slit for releasing stress in said flexible substrate, said first slit having a connector for connecting ~~both sides~~ parts of the first slit and separating said parts in a width-wise direction of said flexible substrate;

a second slit having no connector, for folding said flexible substrate; and

a rib formed substantially perpendicular to the first slit.

11. (Original) The tape carrier type semiconductor device according to claim 10, a portion of said flexible substrate is changed in shape, thereby to form the rib.

12. (Canceled)

13. (Currently Amended) A flexible substrate, comprising:

a first slit for releasing a stress, said first slit having a connector ~~thereto~~ for connecting ~~both sides ends~~ parts of the first slit and separating said parts in a width-wise direction of said flexible substrate, and on whose surface wiring having a predetermined pattern is formed; and

a second slit having no connector, for folding said flexible substrate.

14. (Currently Amended) The flexible substrate according to claim 13, wherein ~~the first slit includes~~ said connector comprises a plurality of connectors.

15. (Currently Amended) The flexible substrate according to claim 14, wherein said parts of the slit, which are separated from each other at the connector, are diverged from each other at the connector in a direction perpendicular to the slit.

16. (Canceled)

17. (Currently Amended) The flexible substrate according to claim ~~16~~ 13, further comprising a rib formed substantially perpendicular to the first slit.

18. (Currently amended) The flexible substrate according to claim 13, wherein a portion of said flexible substrate is changed in shape, thereby to form ~~the~~ a rib.

19. (Canceled)

20. (Canceled)

21. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises at least one of a polyimide resin film, an organic polymer film, a polyamide resin film, a polyester resin film and a composite film.

22. (Previously Presented) The tape carrier type semiconductor device according to claim 1,

wherein said flexible substrate comprises a terminal area adjacent said first slit.

23. (Previously Presented) The tape carrier type semiconductor device according to claim 22, wherein said first slit is situated between said driver circuit and said terminal area, said first slit comprises a rectangular shape with a longitudinal side parallel to said terminal area.

24. (Currently Amended) The tape carrier type semiconductor device according to claim 1, wherein ~~said~~ a warpage of said tape carrier type semiconductor device is no more than approximately 4.8% of a length of said tape carrier type semiconductor device.

25. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said first slit and said second slit are formed on opposing sides of said driver circuit.

26. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises a resin on a first side of said flexible substrate, said resin including a first heat expansion coefficient.

27. (Previously Presented) The tape carrier type semiconductor device according to claim 26, wherein said flexible substrate comprises a solder resist on a second side of said flexible substrate, said solder resist including a second heat expansion coefficient.

28. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said rib comprises a reinforcement rib.

29. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said rib has at least one of a concave and a convex shape.

30. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said first slit comprises a thermal stress-releasing slit.

31. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises a terminal area substantially adjacent to said first slit and said print substrate.

32. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises a terminal area, said first slit is situated between said driver circuit and said terminal area.

33. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said first slit comprises a length of approximately 26 mm, a width of approximately 1.0 mm, and

wherein said connector comprises a width of approximately 1.0 mm.

34. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises a plurality of first slits, which are oriented in an off-set pattern to diverge from a straight line.

35. (Previously Presented) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate is connected to a print substrate, said first slit is substantially adjacent to said driver circuit and said print substrate.